Amendment to the Specification

Please replace the paragraph beginning with "Referring to Fig. 1 . . ." at page 21, line 1, with the following new paragraph.

-- ~~Referring to Fig. 1,~~In vias plated using different concentrations of MPS ~~are shown in cross-sections. As can be seen~~, the covering power became low as the amount of MPS was increased. The via-filling property became low as the amount of MPS was increased and with the MPS concentration of 25μg/L or higher, the via-filling property became insufficient. --

Please replace the paragraph beginning with "Referring to Fig. 2 . . ." at page 21, line 14, with the following new paragraph.

-- ~~Referring to Fig. 2, vias~~Vias plated using different concentrations of MPS ~~are shown in cross-sections. As can be seen, Example 3~~, to which formaldehyde had been added, exhibited a substantially perfect via-filling property at both MPS concentrations of 50μg/L and 100μg/L, though the via-filling property at 100μg/L was slightly lower than that at 50μg/L. In comparison, as described above, the via-filling property was insufficient at the MPS concentrations of 50μg/L and 100μg/L in Example 2, which was formaldehyde-free. These results suggest that formaldehyde has an ability to compensate for the reduction in the via-filling property of the electrolytic copper plating solution, which is imparted by MPS. Accordingly, it has been proven that the electrolytic copper plating solution can be controlled through addition of formaldehyde. --